SOLID STATE OPTRONICS



STR8082

Random Phase
800V / 0.8A
AC Solid State Relay

Description

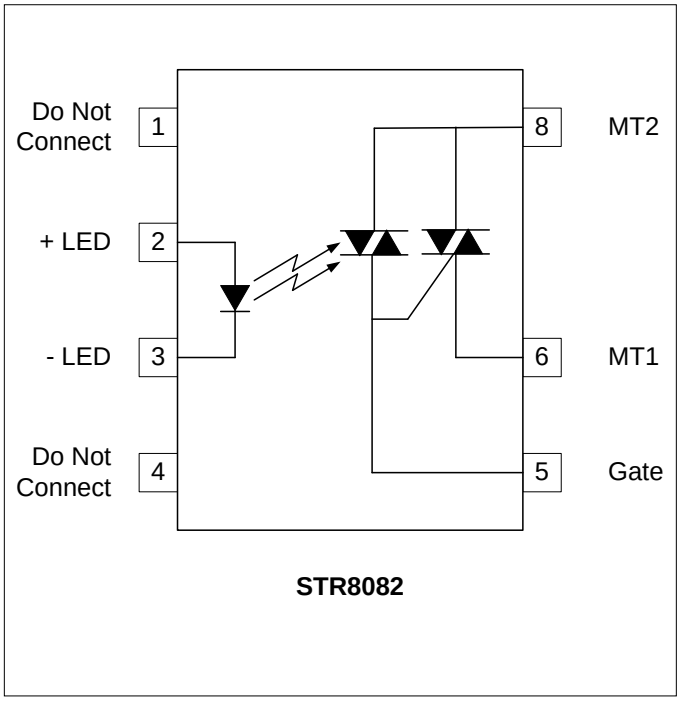
The STR8082 is a bi-directional, single-pole, single-throw, normally open multipurpose relay. The device consists of an IR LED optically coupled to a random phase switching AC output structure. It has a high blocking voltage (800V) and can handle continuous load currents of up to $0.8A_{RMS}$. The STR8082 assures no false triggering under adverse conditions.

The STR8082 comes standard in a compact 8 pin DIP package. The package construction makes it ideal for high-density board applications.

Applications

- Valve Control
- Meter Reading Systems
- Heating Elements
- Home Appliances
- Solenoid / Motor Control
- Dimmer Control

Schematic Diagram



STR8082

Features

- High Blocking Voltage (800V)
- $0.8A_{RMS}$ Continuous Load Current
- Random Phase Switching
- Low Control Current (<10mA)
- High Isolation Voltage (up to $5kV_{RMS}$)
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

Agency Approvals

- UL
- C-UL

Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature .....-55 to +125°C
Operating Temperature .....-40 to +85°C
Continuous Input Current.....50mA
Transient Input Current 500mA
Reverse Input Control Voltage 5V
Input Power Dissipation.....40mW
Output Power Dissipation 800mW
Solder Temperature – Wave (10sec).....260°C
Solder Temperature – IR Reflow (10sec).....260°C

Ordering Information

Part Number	Description
STR8082	8 pin DIP, (50/Tube)
STR8082-H	$5kV_{RMS}$ Viso, 8 pin DIP, (50/Tube)
STR8082-S	8 pin SMD, (50/Tube)
STR8082-HS	$5kV_{RMS}$, 8 pin SMD, (50/Tube)
STR8082-STR	8 pin SMD, Tape and Reel (1000/Reel)
STR8082-HSTR	$5kV_{RMS}$, 8 pin SMD, Tape and Reel (1000/Reel)

NOTE: Suffixes listed above are not included in marking on device for part number identification

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STR8082 H/S/TR
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Electrical Characteristics, T_A = 25°C (unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Input Specifications						
LED Forward Voltage	V_F	-	1.4	1.8	V	I_F = 10mA
LED Reverse Voltage	BV_R	5	-	-	V	I_R = 10µA
Trigger Current [1]	I_{FT}	-	-	10	mA	Resistive Load
Output Specifications						
Peak Off-State Voltage	V_{DRM}	800	-	-	V	I_{DRM}=10µA
Continuous Load Current	$I_{T(RMS)}$	-	-	0.8	A	I_{FT}=10mA
Peak On-State Voltage	V_{TM}	-	1.3	2.5	V	I_{FT}=10mA, I_T=800mA
Leakage Current	I_{DRM}	-	10	100	µA	I_{FT}=0mA, V_{DRM}=800V
Holding Current	I_H	-	5	25	mA	I_{FT}=10mA
Critical Rate of Rise (dV//dt)	dV_D/dt	-	-	400	V/µS	V_{DM}=67% 800V
Isolation Specifications						
Isolation Voltage	V_{ISO}	3750	-	-	V_{RMS}	RH ≤ 50%, t=1min
(-H Option)		5000	-	-		
Input-Output Resistance	R_{I-O}	-	10^{12}	-	Ω	V_{I-O} = 500V_{DC}

Notes:

1) I_{FT} = 20mA recommended for inductive loads

STR8082 Performance & Characteristics Plots, T_A = 25°C (unless otherwise specified)

Figure 1: *Typical Trigger Current Distribution*
(Resistive Load, N = 100, T_a = 25ºC)

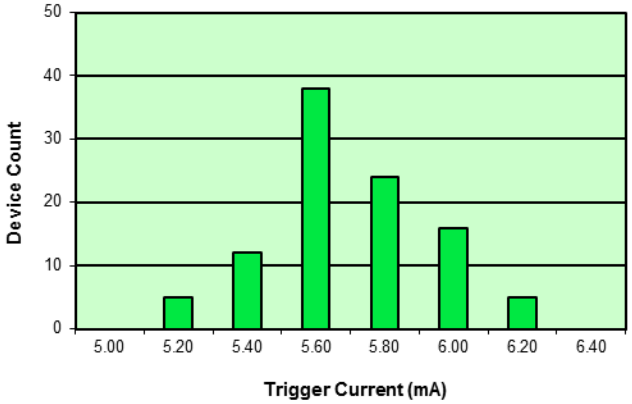


Figure 2: *Typical Peak Off-State Voltage Distribution*
(N = 100, Ta = 25ºC)

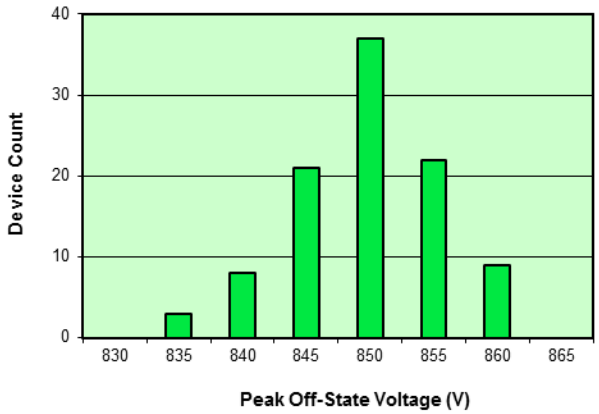


Figure 3: *On-State Voltage vs. Temperature*

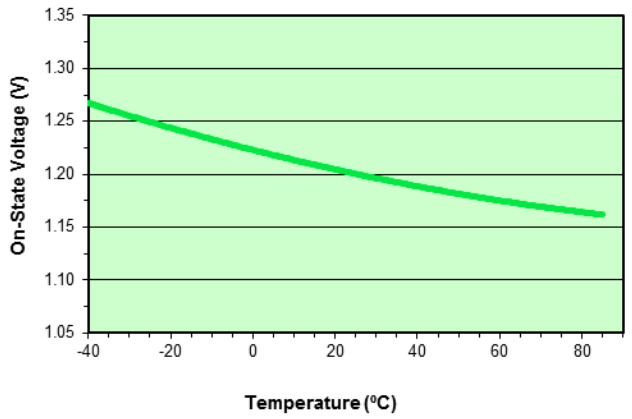


Figure 4: *Maximum Load Current vs. Temperature*

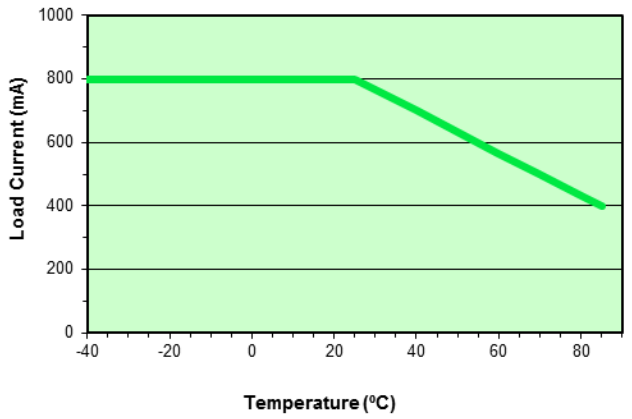
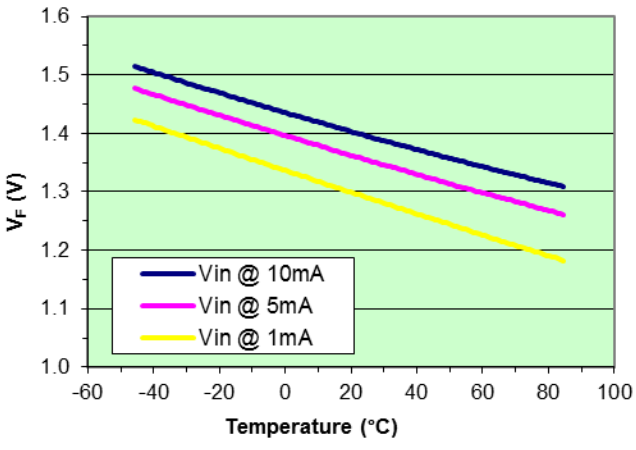


Figure 5: *Typical LED Voltage vs Temperature*



STR8082 Solder Temperature Profile Recommendations

(1) *Infrared Reflow:*

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250ºC:

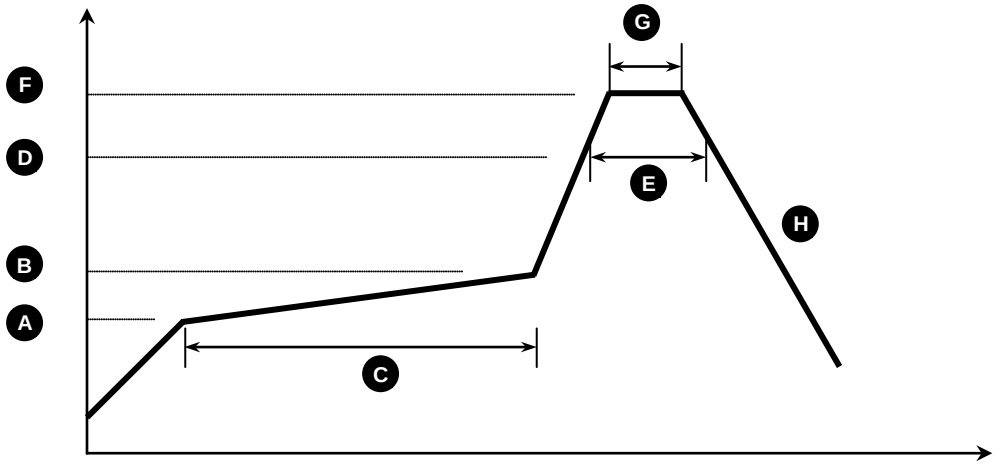


Figure 1

Process Step	Description	Parameter
A	Preheat Start Temperature (ºC)	150ºC
B	Preheat Finish Temperature (ºC)	180ºC
C	Preheat Time (s)	90 - 120s
D	Melting Temperature (ºC)	230ºC
E	Time above Melting Temperature (s)	30s
F	Peak Temperature, at Terminal (ºC)	260ºC
G	Dwell Time at Peak Temperature (s)	10s
H	Cool-down (ºC/s)	<6ºC/s

(2) *Wave Solder:*

Maximum Temperature:	260ºC (at terminal)
Maximum Time:	10s
Pre-heating:	100 - 150ºC (30 - 90s)
Single Occurrence	

(3) *Hand Solder:*

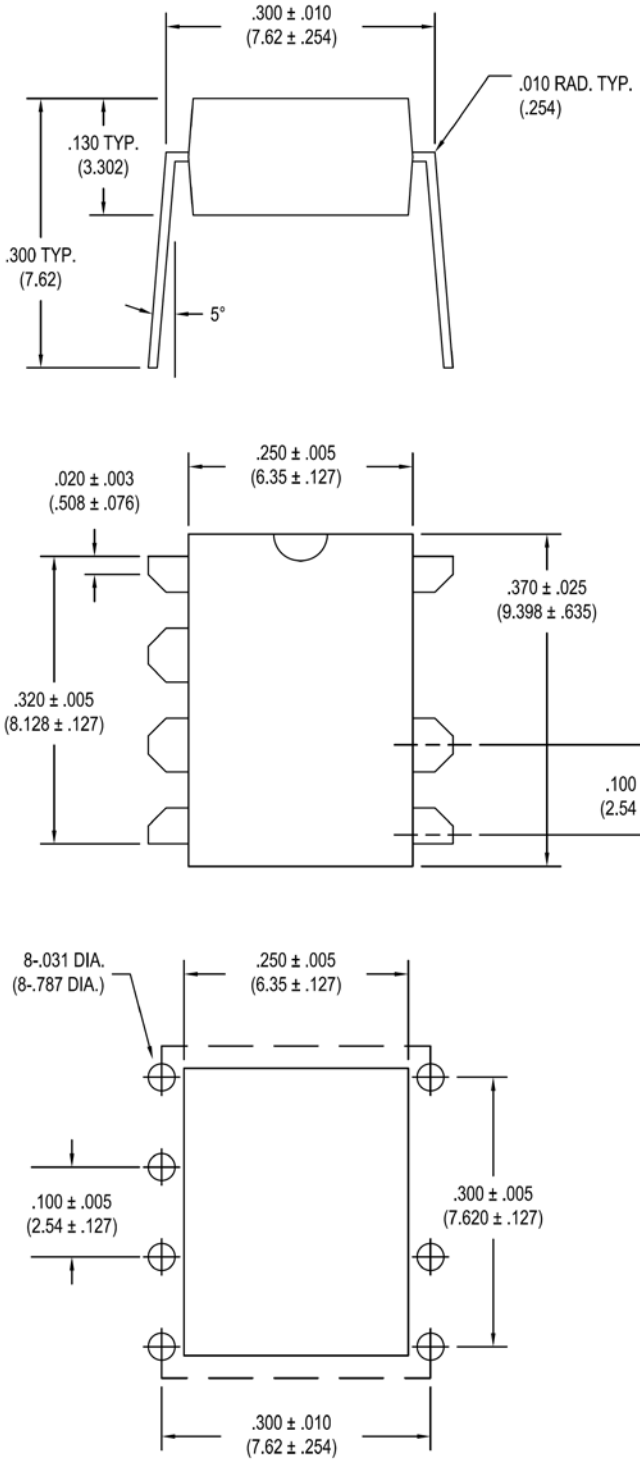
Maximum Temperature:	350ºC (at tip of soldering iron)
Maximum Time:	3s
Single Occurrence	

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STR8082 Package Dimensions

8 PIN DIP Package

Note: *All dimensions in inches ["] with millimeters in parenthesis ()*

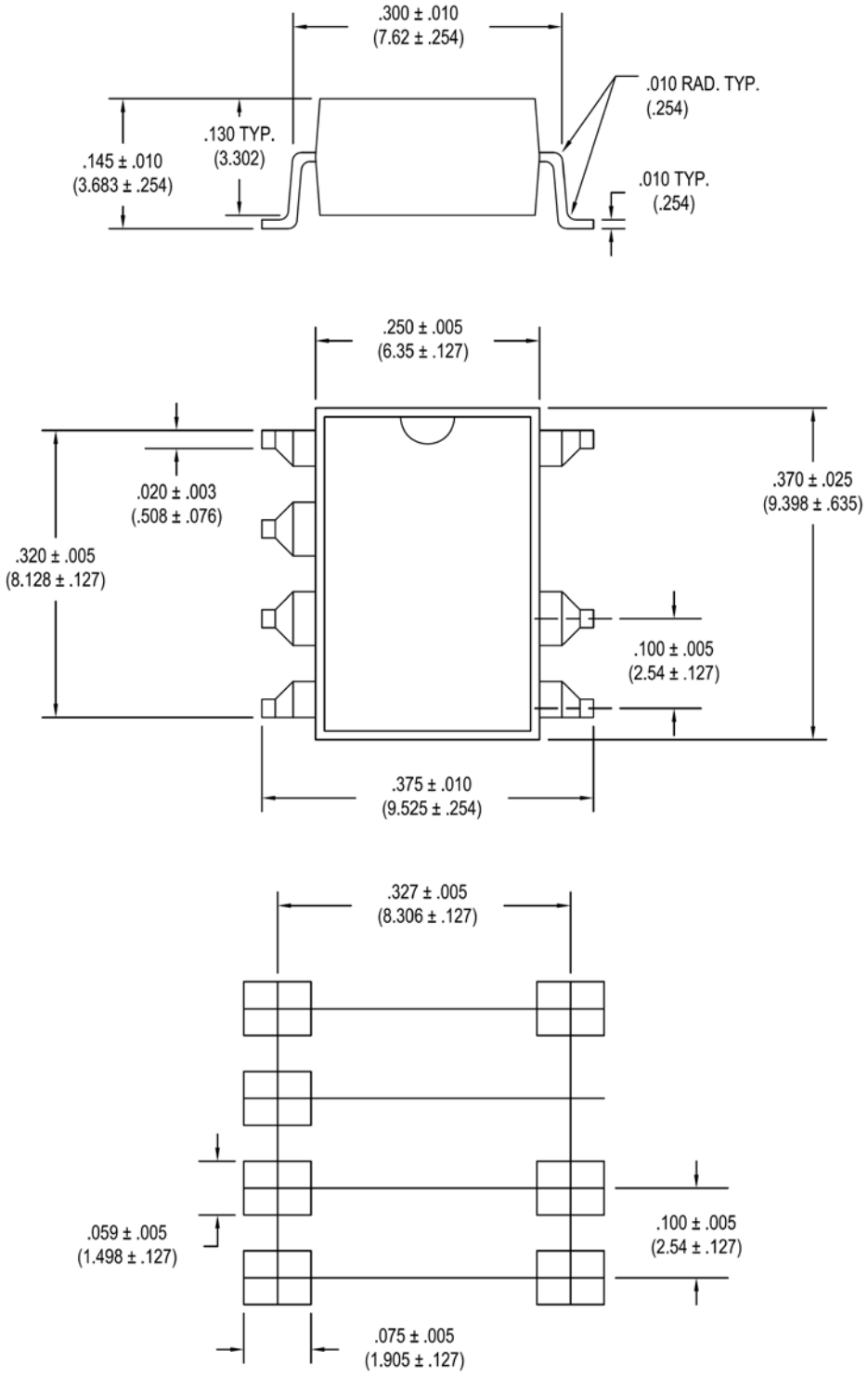


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STR8082 Package Dimensions

8 PIN SMD Surface Mount Package (-S)

Note: *All dimensions in inches ["] with millimeters in parenthesis ()*



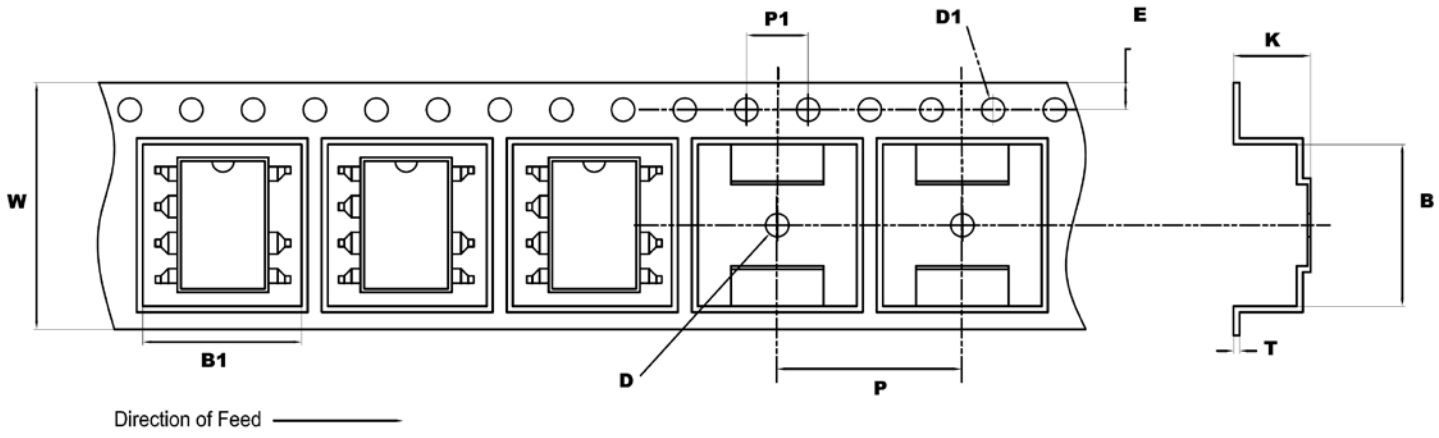
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STR8082 Package Dimensions

8 PIN SMD Tape & Reel (-STR)

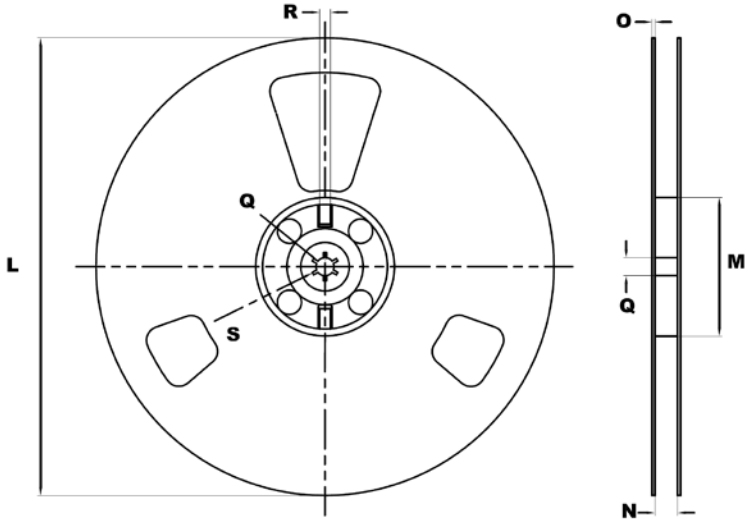
Note: *All dimensions in millimeters*

Outline and Dimension (Tape)



W	B	B1	P	P1	K	E	T	D	D1
16.00 ±0.1	10.50 ±0.1	10.30 ±0.1	12.00 ±0.1	4.00 ±0.1	5.00 ±0.1	1.75 ±0.1	0.40 ±0.1	1.50 ±0.1	1.50 ±0.1

Outline and Dimensions (Reel)

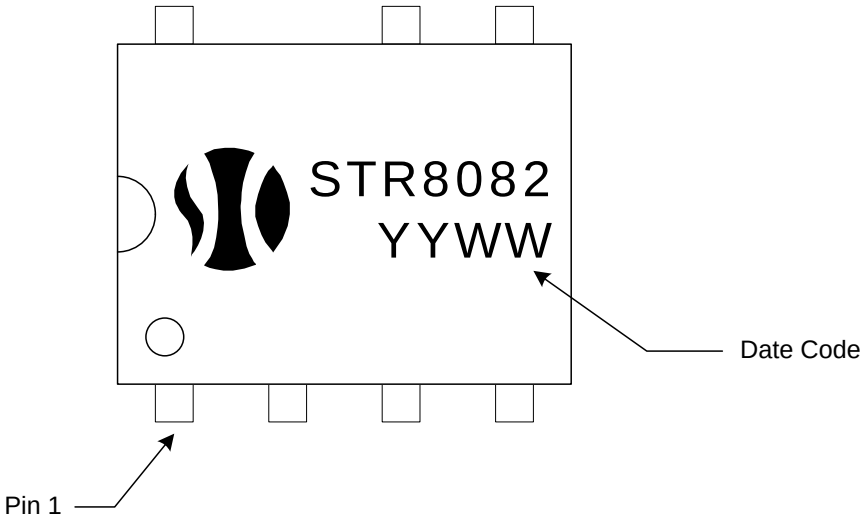


Packaging: 1,000 pcs / reel

L	M	N	O	Q	R	S
330.00	100.00	16.40 +0.2	2.00 ±0.1	13.00 ±0.2	2.00	10.00

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STR8082 Package Marking



STR8082 Package Weights

Device	Single Unit	Full Tube (50pcs)	Full Pouch (10 tubes)	Full Reel (1000pcs)
STR8082-(H)	0.54	42	420	-
STR8082-(H)S	0.53	44	440	-
STR8082-(H)STR	0.53	-	-	950

Note: *All weights above are in GRAMS, and include packaging materials where applicable*

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